



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Prindiville et al.

Application No. 09/971,952

Filed: October 4, 2001

For: SEMICONDUCTOR PACKAGES AND  
METHODS FOR MAKING THE SAME

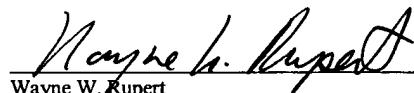
Examiner: Lourdes C. Cruz

Date: June 24, 2002

Art Unit: 2827

CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service on June 24, 2002 as First Class Mail in an envelope addressed to: COMMISSIONER FOR PATENTS, WASHINGTON, D.C. 20231.



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**REPLY TO OFFICE ACTION**

This is a reply to a non-final Office Action mailed March 22, 2002. A reply is due by June 22, 2002, which is a Saturday, making the reply due by June 24, 2002. Reconsideration and withdrawal of the pending rejections is respectfully requested. A Letter to the Official Draftsperson submitting corrected drawings of FIGS. 1A, 3A and 3B accompanies this reply.

**In the claims:**

Please add the following claims:

36. (New) The defective semiconductor package of claim 30, wherein the cover member covers from about 70% to about 98% of the opening formed by the wire bond slot.

37. (New) The defective semiconductor package of claim 30, wherein the wire bond slot is associated with the defective die attach site.

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